Dual Unbuffered Inverter

The NLX2GU04 MiniGate $^{\text{TM}}$ is an advanced high-speed CMOS dual unbuffered inverter in ultra-small footprint.

This device is well suited for use in oscillator, pulse-shaping and high input impedance amplifier applications. For digital applications, the NLX2G04 is recommended.

The NLX2GU04 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Unbuffered for Crystal Oscillator and Analog Applications
- 16 mA Balanced Output Source and Sink Capability
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

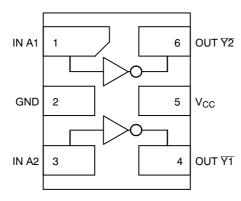


Figure 1. Pinout (Top View)

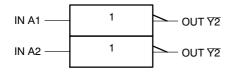


Figure 2. Logic Symbol



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS



ULLGA6 1.0 x 1.0 CASE 613AD





ULLGA6 1.2 x 1.0 CASE 613AE





ULLGA6 1.45 x 1.0 CASE 613AF



L = Device MarkingM = Date Code

PIN ASSIGNMENT

1	IN A1			
2	GND			
3	IN A2			
4	OUT Y2			
5	V _{CC}			
6	OUT Y1			

FUNCTION TABLE

Α	₹
L	H
H	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parame	Value	Unit	
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V	
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
lok	DC Output Diode Current	V _{OUT} < GND	-50	mA
I _O	DC Output Source/Sink Current		±50	mA
I _{CC}	DC Supply Current Per Supply Pin	±100	mA	
I _{GND}	DC Ground Current per Ground Pin	±100	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
T _L	Lead Temperature, 1 mm from Case for 10 S	econds	260	°C
T _J	Junction Temperature Under Bias	150	°C	
MSL	Moisture Sensitivity	Level 1		
F _R	Flammability Rating Oxygen	UL 94 V-0 @ 0.125 in		
I _{LATCHUP}	Latchup Performance Above $V_{\mbox{\footnotesize CC}}$ and Below	±500	mA	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
 Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/UESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V	
V _{IN}	Digital Input Voltage	0	5.5	V	
V _{OUT}	Output Voltage	0	5.5	V	
T _A	Operating Free-Air Temperature			+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

				T _A = 25 °C		T _A = 25 °C		T _A = +	+85°C		55°C to 5°C	
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Min	Max	Unit	
V _{IH}	Low-Level Input Voltage		1.65 2.3 to 5.5	0.85 x V _{CC} 0.80 x V _{CC}			0.85 x V _{CC} 0.80 x V _{CC}		0.85 x V _{CC} 0.80 x V _{CC}		V	
V _{IL}	Low-Level Input Voltage		1.65 2.3 to 5.5			0.15 x V _{CC} 0.20 x V _{CC}		0.15 x V _{CC} 0.20 x V _{CC}		0.15 x V _{CC} 0.20 x V _{CC}	V	
V _{OH}	High- Level Output	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -100 \mu A$	1.65 to 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V _{CC} - 0.1		V	
	Voltage	$\begin{aligned} &V_{\text{IN}} = V_{\text{IH}} \text{ or } V_{\text{IL}} \\ &I_{\text{OH}} = -3 \text{ mA} \\ &I_{\text{OH}} = -4 \text{ mA} \\ &I_{\text{OH}} = -6 \text{ mA} \\ &I_{\text{OH}} = -8 \text{ mA} \\ &I_{\text{OH}} = -12 \text{ mA} \\ &I_{\text{OH}} = -16 \text{ mA} \end{aligned}$	1.65 2.3 2.7 3.0 3.0 4.5	1.29 1.9 2.2 2.4 2.3 3.8	1.52 2.1 2.3 2.6 2.5 4.0		1.29 1.9 2.2 2.4 2.3 3.8		1.29 1.9 2.2 2.4 2.3 3.8			
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu\text{A}$	1.65 to 5.5			0.1		0.1		0.1	V	
	vollage	$\begin{aligned} &V_{\text{IN}} = V_{\text{IH}} \text{ or } V_{\text{IL}} \\ &I_{\text{OH}} = 3 \text{ mA} \\ &I_{\text{OH}} = 4 \text{ mA} \\ &I_{\text{OH}} = 6 \text{ mA} \\ &I_{\text{OH}} = 8 \text{ mA} \\ &I_{\text{OH}} = 12 \text{ mA} \\ &I_{\text{OH}} = 16 \text{ mA} \end{aligned}$	1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.12 0.2 0.24 0.36 0.31	0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55		
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ	
I _{OFF}	Power-Off Output Leakage Current	V _{OUT} = 5.5 V	0			1.0		10		10	μΑ	
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		10		10	μΑ	

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

		V _{CC}		т	' _A = 25 °(С	T _A = - to +1		
Symbol	Parameter	(V)	Test Condition	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay, Input A to Output Y	1.65 to 1.95	$R_L = 1 M\Omega,$ $C_L = 15 pF$	1.5	1.8	5.5	1.5	11	ns
		2.3 to 2.7	$R_L = 1 M\Omega,$ $C_L = 15 pF$	1.2	3.3	5.7	1.2	6.3	
		3.0 to 3.6	$R_L = 1 M\Omega,$ $C_L = 15 pF$	0.8	2.7	4.1	0.8	4.5	
			$R_L = 500 \Omega$, $C_L = 50 pF$	1.2	4.0	6.4	1.2	7.0	
		4.5 to 5.5	$R_L = 1 M\Omega,$ $C_L = 15 pF$	0.5	2.2	3.3	0.5	3.6	
			$R_L = 500 \Omega$, $C_L = 50 pF$	0.8	3.4	5.6	0.8	6.2	
C _{IN}	Input Capacitance	5.5	V _{IN} = 0 V or V _{CC}		7				pF
C _{OUT}	Output Capacitance	5.5	V _{IN} = 0 V or V _{CC}		8			_	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	5.5	10 MHz V _{IN} = 0 V or V _{CC}		25				pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

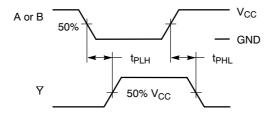
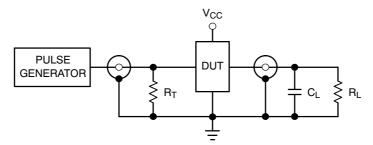


Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

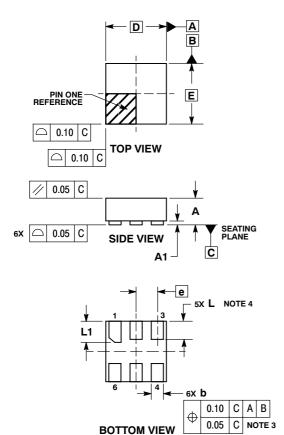
ORDERING INFORMATION

Device	Package	Shipping [†]
NLX2GU04AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2GU04BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2GU04CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

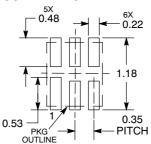
ULLGA6 1.0x1.0, 0.35P CASE 613AD-01 **ISSUE A**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED. PACKAGE IS ALLOWED.

$\overline{}$						
_	MILLIMETERS					
DIM	MIN	MAX				
Α	-	0.40				
A1	0.00	0.05				
b	0.12	0.22				
D	1.00	BSC				
Е	1.00 BSC					
е	0.35 BSC					
L	0.25	0.35				
L1	0.30 0.40					

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

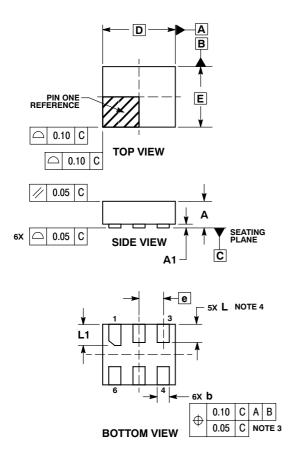


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

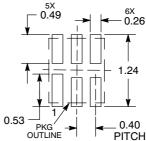
ULLGA6 1.2x1.0, 0.4P CASE 613AE-01 ISSUE A



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

Γ		MILLIMETERS						
П	DIM	MIN	MAX					
Γ	Α		0.40					
	A1	0.00	0.05					
	b	0.15	0.25					
	D	1.20 BSC						
Г	Е	1.00 BSC						
	е	0.40 BSC						
	L	0.25	0.35					
Г	L1	0.35	0.45					

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

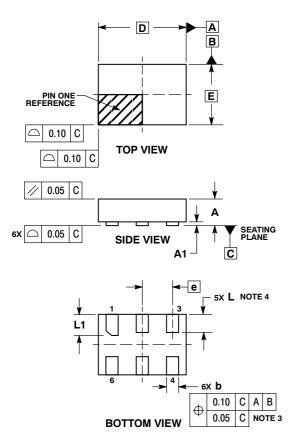


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.45x1.0, 0.5P CASE 613AF-01 **ISSUE A**

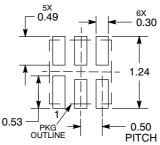


NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
- A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS					
DIM	MIN	MAX				
Α		0.40				
A1	0.00	0.05				
b	0.15	0.25				
D	1.45 BSC					
E	1.00 BSC					
е	0.50	BSC				
L	0.25	0.35				
L1	0.30	0.40				

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MiniGate is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and are registered readerlands of semiconductor components industries, ILC (SciLLC). SciLLC reserves are right to finate dranges without further holice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative